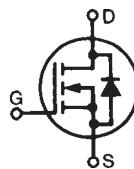


TrenchTTM Power MOSFET

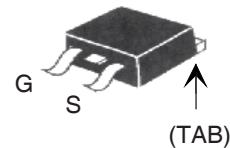
N-Channel Enhancement Mode
Avalanche Rated

IXTA300N04T2 IXTP300N04T2

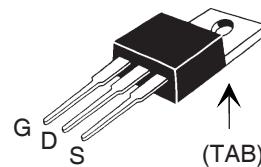
V_{DSS} = 40V
I_{D25} = 300A
R_{DS(on)} ≤ 2.5mΩ



TO-263 (IXTA)



TO-220 (IXTP)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 175°C	40	V
V _{DGR}	T _J = 25°C to 175°C, R _{GS} = 1MΩ	40	V
V _{GSM}	Transient	± 20	V
I _{D25}	T _C = 25°C	300	A
I _{LRMS}	Lead Current Limit, RMS	75	A
I _{DM}	T _C = 25°C, pulse width limited by T _{JM}	900	A
I _A	T _C = 25°C	100	A
E _{AS}	T _C = 25°C	600	mJ
P _D	T _C = 25°C	480	W
T _J		-55 ... +175	°C
T _{JM}		175	°C
T _{stg}		-55 ... +175	°C
T _L	1.6mm (0.062in.) from case for 10s	300	°C
T _{sold}	Plastic body for 10 seconds	260	°C
M _d	Mounting torque (TO-220)	1.13 / 10	Nm/lb.in.
Weight	TO-263	2.5	g
	TO-220	3.0	g

Symbol	Test Conditions (T _J = 25°C unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 250μA	40		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0		V
I _{GSS}	V _{GS} = ± 20V, V _{DS} = 0V		±200	nA
I _{DSS}	V _{DS} = V _{DSS} V _{GS} = 0V		5	μA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Notes 1, 2		150	μA
			2.5	mΩ

Features

- International standard packages
- 175°C Operating Temperature
- Avalanche rated
- High current handling capability
- Low R_{DS(on)}

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- Synchronous Buck Converters
- High Current Switching Power Supplies
- Battery Powered Electric Motors
- Resonant-mode power supplies
- Electronics Ballast Application
- Class D Audio Amplifiers

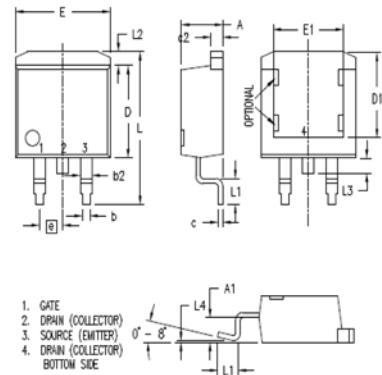
Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	55	94	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	10.7	nF	
		1630	pF	
		263	pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 100\text{A}$ $R_G = 2\Omega$ (External)	22	ns	
		17	ns	
		32	ns	
		13	ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$	145	NC	
		44	NC	
		36	NC	
R_{thJC}			0.31	$^\circ\text{C}/\text{W}$
R_{thCH}	TO-220	0.50		$^\circ\text{C}/\text{W}$

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	$V_{GS} = 0\text{V}$		300	A
I_{SM}	Repetitive, Pulse width limited by T_{JM}		1000	A
V_{SD}	$I_F = 100\text{A}$, $V_{GS} = 0\text{V}$, Note 1		1.3	V
t_{rr} I_{RM} Q_{RM}	$I_F = 150\text{A}$, $V_{GS} = 0\text{V}$ $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 20\text{V}$	53	ns	
		1.8	A	
		47.7	NC	

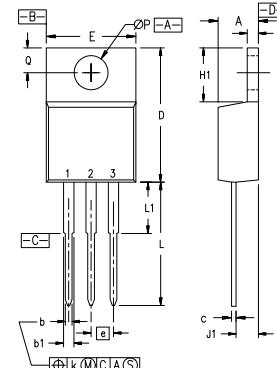
Notes: 1. Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.
 2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5mm or less from the package body.

TO-263 (IXTA) Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100	BSC	2.54	BSC
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-220 (IXTP) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4 - Drain

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100	BSC	2.54	BSC
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

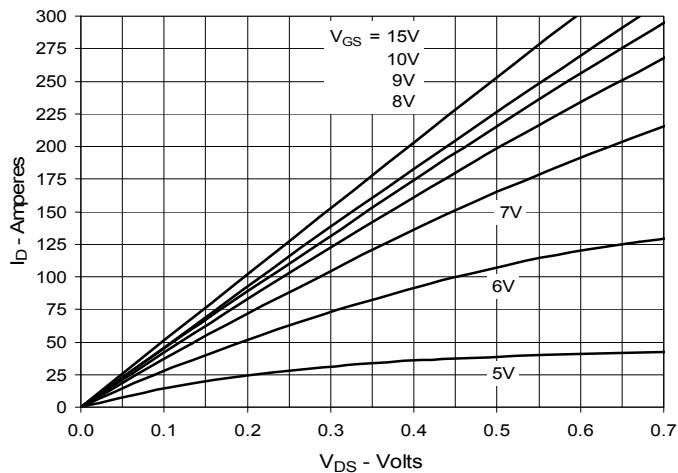
PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

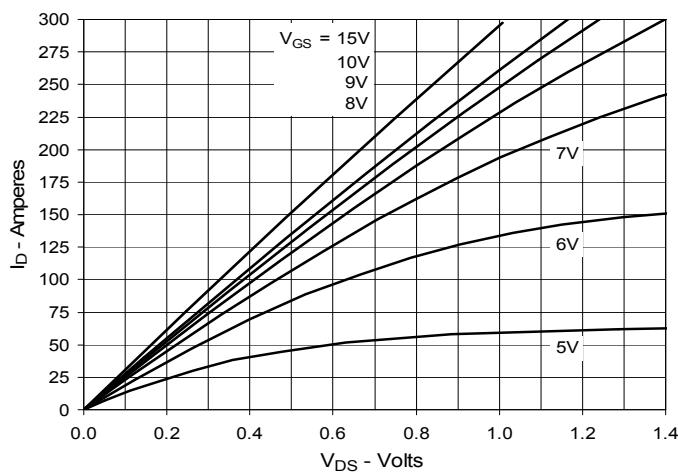
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

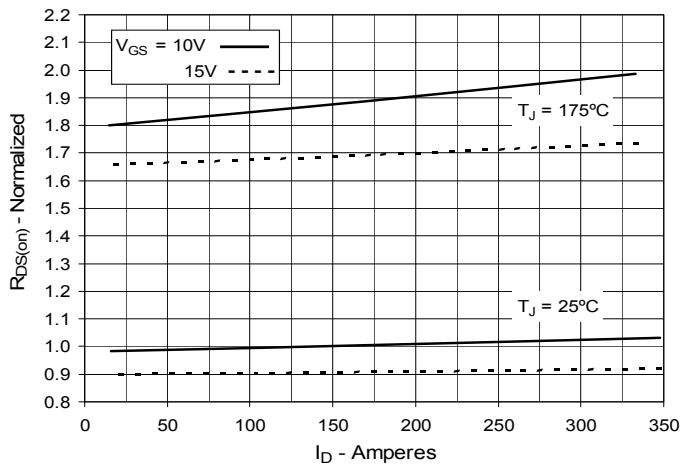
**Fig. 1. Output Characteristics
@ 25°C**



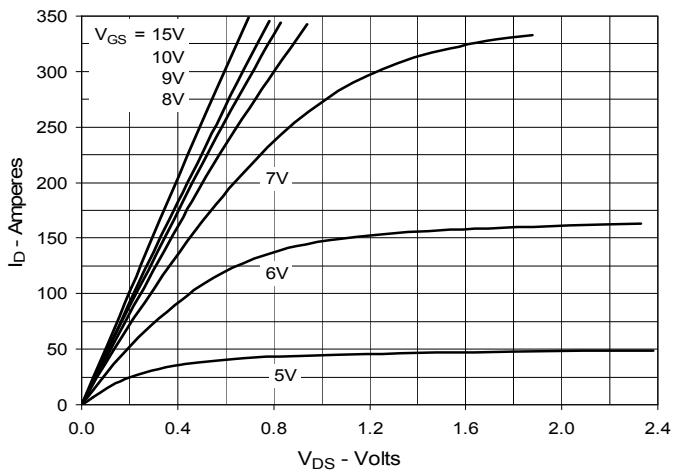
**Fig. 3. Output Characteristics
@ 150°C**



**Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 150A$ Value
vs. Drain Current**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 150A$ Value
vs. Junction Temperature**

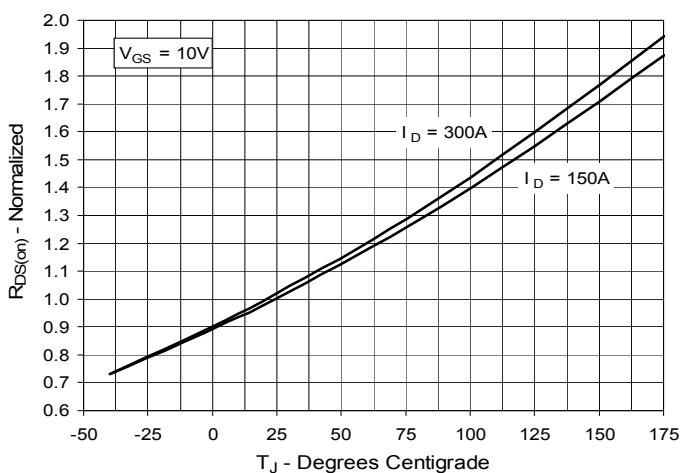


Fig. 6. Drain Current vs. Case Temperature

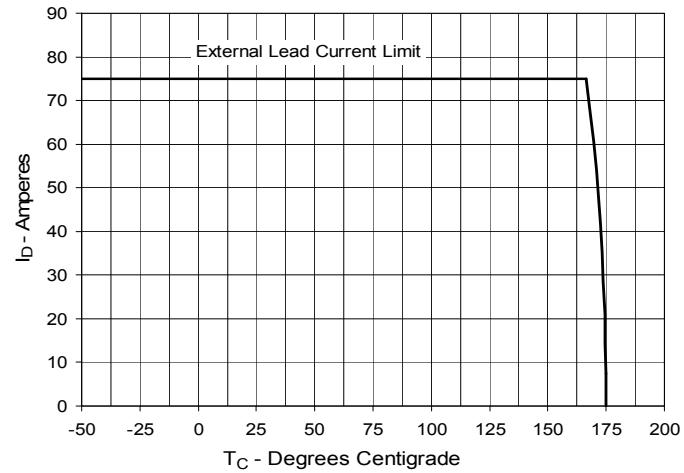
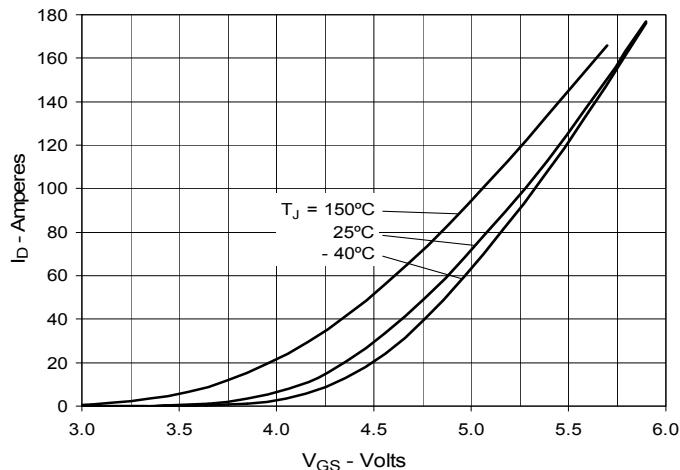
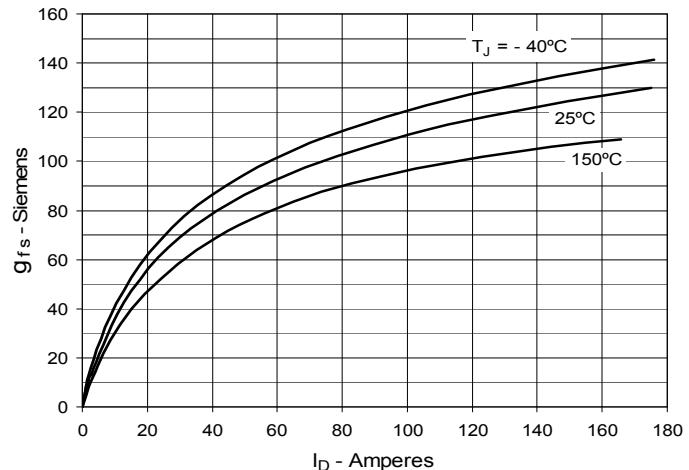
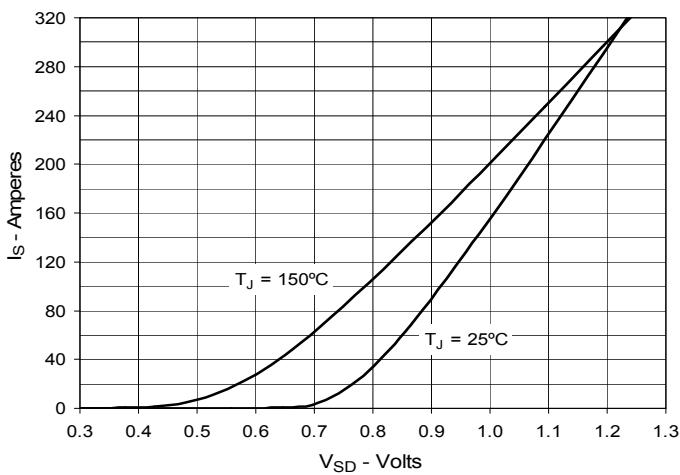
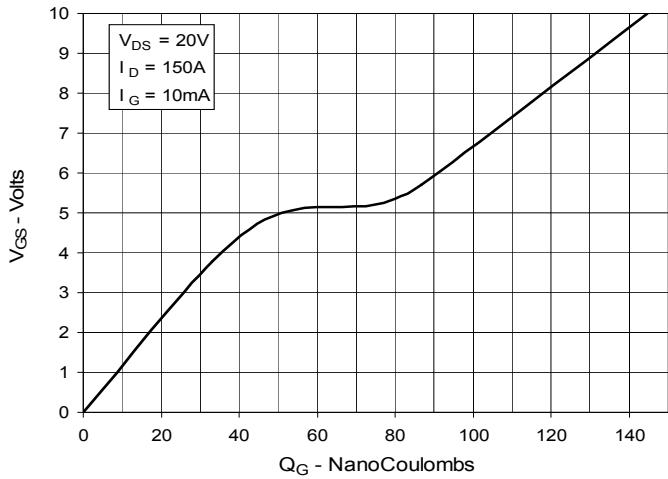
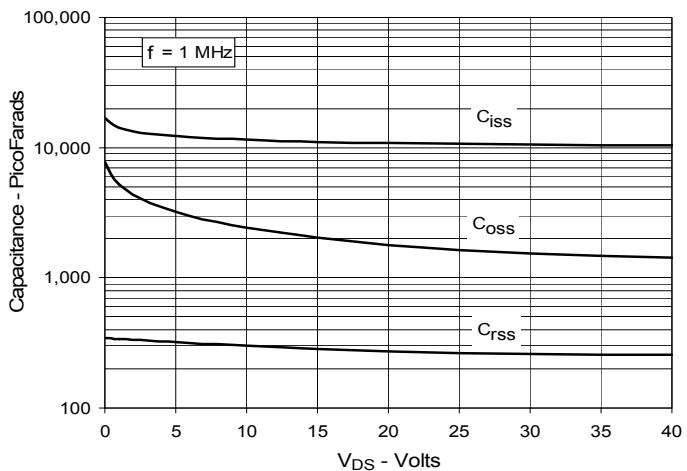
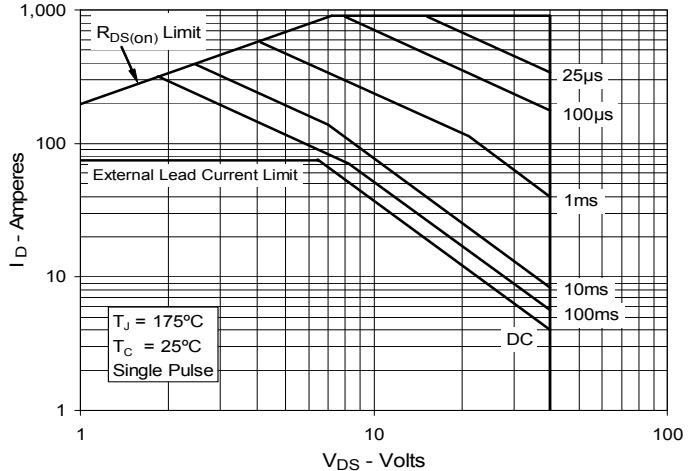
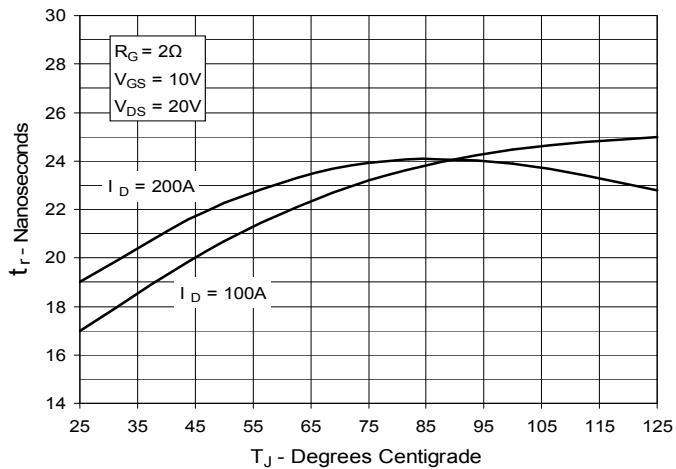


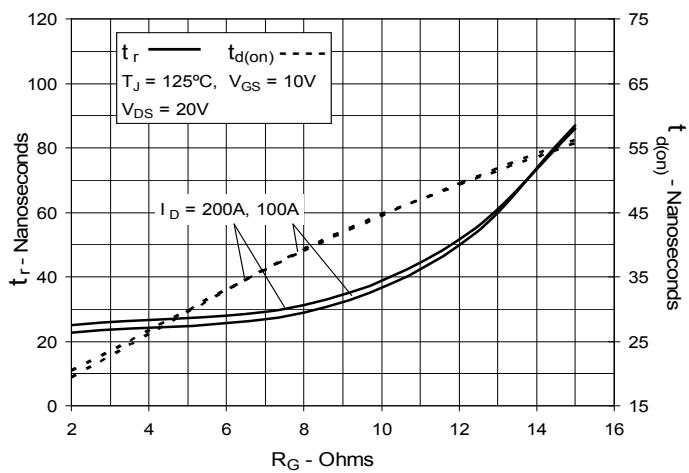
Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Forward Voltage Drop of Intrinsic Diode

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Forward-Bias Safe Operating Area


IXYS reserves the right to change limits, test conditions, and dimensions.

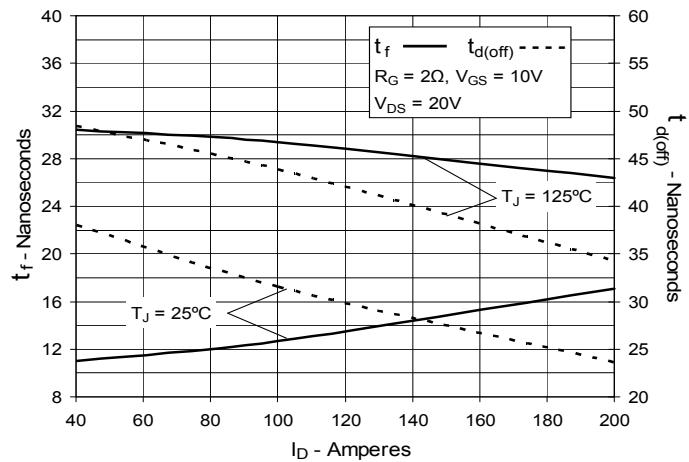
**Fig. 13. Resistive Turn-on
Rise Time vs. Junction Temperature**



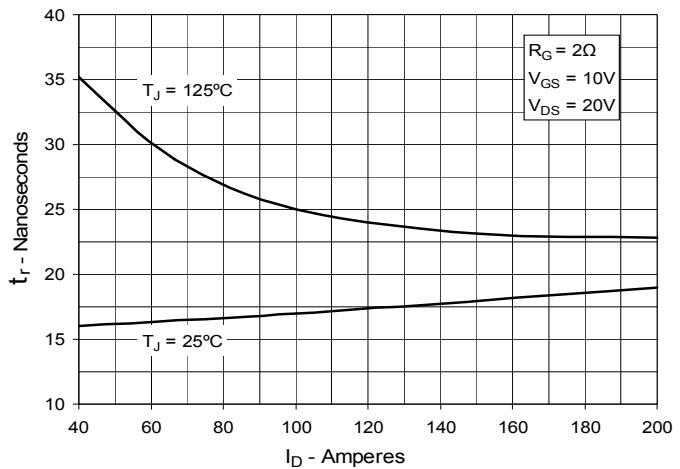
**Fig. 15. Resistive Turn-on
Switching Times vs. Gate Resistance**



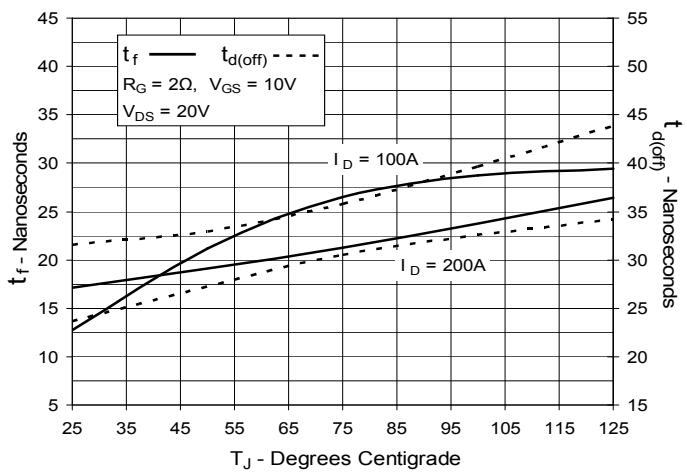
**Fig. 17. Resistive Turn-off
Switching Times vs. Drain Current**



**Fig. 14. Resistive Turn-on
Rise Time vs. Drain Current**



**Fig. 16. Resistive Turn-off
Switching Times vs. Junction Temperature**



**Fig. 18. Resistive Turn-off
Switching Times vs. Gate Resistance**

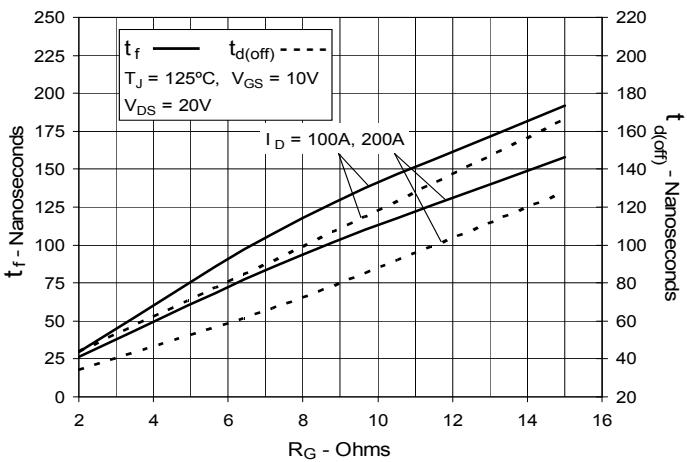


Fig. 19. Maximum Transient Thermal Impedance